DECLARATION OF JOINT INVENTORS FOR PATENT APPLICATION

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the inventor entitled: "Etching Processes for Integrated Circuit Manufacturing Including Methods of Forming Capacitors", the specification of which is attached hereto.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims.

I acknowledge the duty to disclose information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations § 1.56.

PRIOR FOREIGN APPLICATIONS:

I hereby state that no applications for foreign patents or inventor's certificates have been filed prior to the date of execution of this declaration.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statement may jeopardize the validity of the application or any patent issued therefrom.

	\
Full name of inventor:	Paul A. Morgan
Inventor's Signature:	bolom
Date:	9/8/02
Residence:	Kuna, Idano
Citizenship:	United States of America
Post Office Address:	12768 South Cloverdale Road, Kuna, ID 83634
	* * * * * * * * * *
Full name of inventor:	Patrick M. Flynn
Inventor's Signature:	Potel M. Flyn
Date:	2/8/2002
Residence:	Boise, Idaho
Citizenship:	United States of America
Post Office Address:	8809 West Donnybrook Drive, Boise, ID 83709
	* * * * * * * * * *
Full name of inventor:	Janos Fucsko
Inventor's Signature:	Jamos Friko
Date:	2/11/2002
Residence:	Boise, Idaho
Citizenship:	Hungary

1634 Martha Street, No. 101, Boise, ID 83709

Post Office Address:

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No
Filing Date Filed Herewith
Inventor Paul A. Morgan et al.
Assignee Micron Technology, Inc.
Group Art Unit Unknown
Examiner Unknown
Attorney's Docket No
Title: Etching Processes for Integrated Circuit Manufacturing Including Methods of
Forming Capacitors

POWER OF ATTORNEY BY ASSIGNEE AND CERTIFICATE BY ASSIGNEE UNDER 37 CFR § 3.73(b)

To: Assistant Commissioner for Patents

Washington, D.C. 20231

Sir:

MICRON TECHNOLOGY, INC., the Assignee of the entire right, title and interest in the above-identified patent application by assignment attached hereto, hereby appoints the attorneys and agents of the firm of WELLS ST. JOHN P.S., listed as follows:

David P. Roberts	Reg.	No.	23,032
Randy A. Gregory	Reg.	No.	30,386
Mark S. Matkin	Reg.	No.	32,268
James L. Price	Reg.	No.	27,376
Deepak Malhotra	Reg.	No.	33,560
Mark W. Hendricksen	Reg.	No.	32,356
David G. Latwesen	Reg.	No.	38,533
George G. Grigel	Reg.	No.	31,166
Keith D. Grzelak	Reg.	No.	37,144
James D. Shaurette	Reg.	No.	39,833
Frederick M. Fliegel	Reg.	No.	36,138
D. Brent Kenady	Reg.	No.	40,045
James E. Lake	Reg.	No.	44,854
Bernard Berman	Reg.	No.	37,279
Jennifer J. Taylor	Reg.	No.	48,711

and also attorneys Michael L. Lynch (Reg. No. 30,871) and Charles B. Brantley II (Reg. No. 38,086) of Micron Technology, Inc., as its attorneys with full power of substitution to prosecute this application and transact all business in the Patent and Trademark Office connected therewith.

The Assignee certifies that the above-identified Assignment has been reviewed and to the best of Assignee's knowledge and belief, title is in the Assignee, and a copy of the Assignment is submitted herewith.

Please direct all correspondence regarding this application to:

Customer No. 021567 Wells St. John P.S. Attn: Mark S. Matkin

601 West First Avenue, Suite 1300

Spokane, WA 99201-3828 Telephone: (509) 624-4276 Facsimile: (509) 838-3424

MICRON TECHNOLOGY, INC.

Dated: 4.28.62

By:

Name: Roderic W. Lewis

Title:

Vice President, Legal, General Counsel and Corporate Secretary

Attachment: Copy of Assignment